



iPhone X Data Recovery From A Dead Motherboard

iPhone X Data Recovery From A Dead Motherboard; CPU swap on A Dead iPhone X Motherboard

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INTRODUCTION

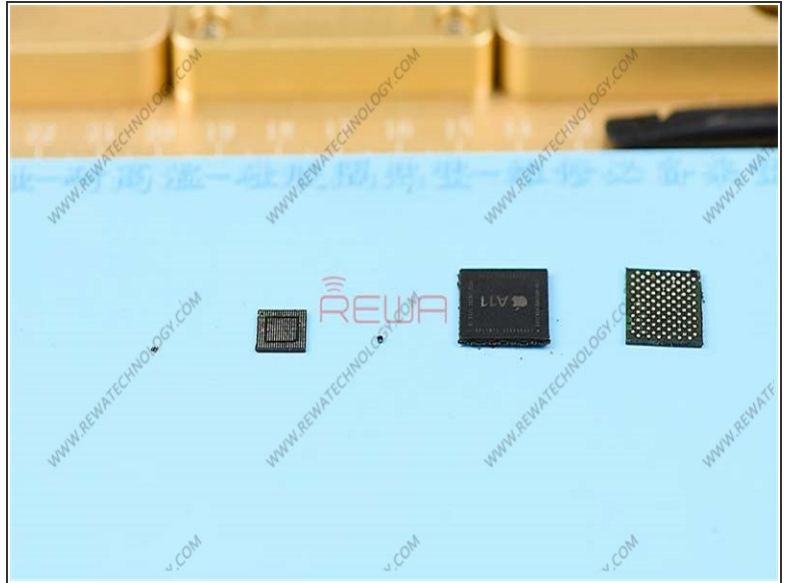
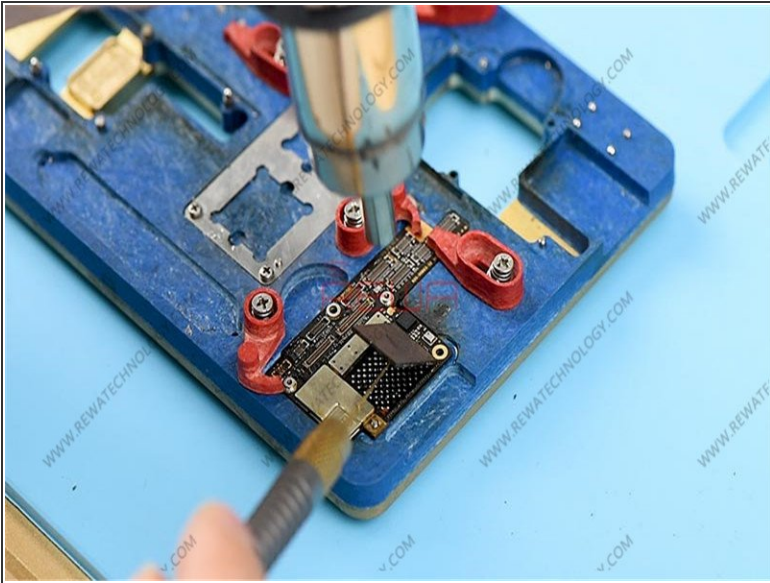
CPU swap for data recovery is rarely required for iPhone X data recovery. Most iPhone X logic boards that don't boot can either be solved by an experienced board level repair technician, or are due to software corruption in which case CPU swap can't help you. However, for some boards with catastrophic hardware damage (like the phone went through a lawnmower) it can be a useful technique. Find a reputable company with experience in iPhone X data recovery before considering an invasive surgery such as described here.

Step 1 — Diagnosis



- The boot current is abnormal. So the PCB board might have been damaged. We can troubleshoot this logic board to solve the problem, or take a risk and transfer the CPU and other unique chips to a receiver board.
- To recover data, we decide in this case to transplant CPU and some other chips to a receiver board.

Step 2 — Board Swap



- Attach the upper layer to the PCB Holder. Heat and pry up the NAND flash chip with a specialized knife.
- Next, let's detach CPU, EEPROM, Baseband CPU and Baseband EEPROM from the board with the same steps. Please know that not all of these chips are required to be transferred for data recovery.

Step 3 — Board Swap



- Now, we need to reball these detached components. Let's start with the NAND flash chip.
- Clean the NAND flash chip first and then reball the chip. Once done, continue to reball the baseband CPU, CPU, EEPROM and baseband EEPROM with the same steps.

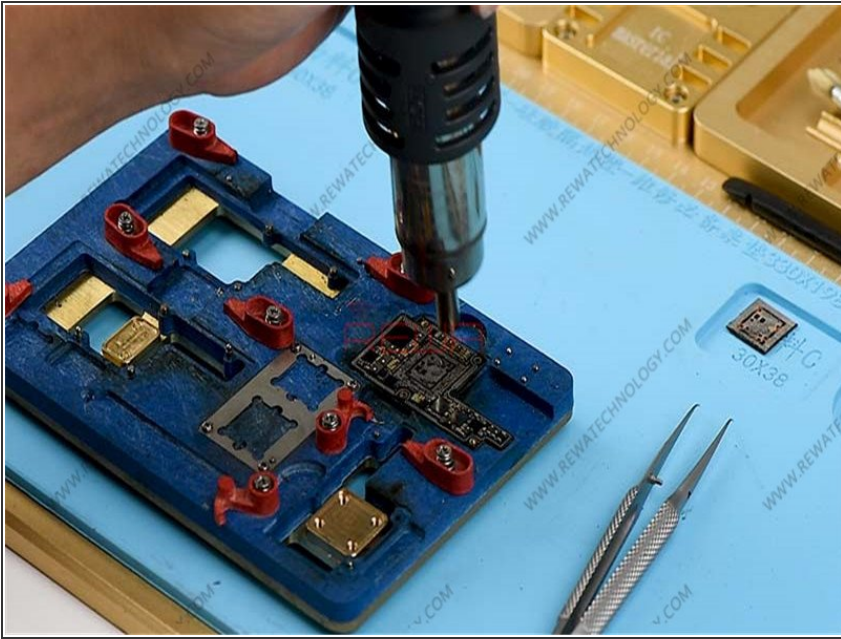
Step 4 — Unbind WiFi



i Please be noted that the WiFi module is bound up with WiFi address stored in the NAND flash chip. So our next move is to unbind WiFi.

- Connect the PCIE NAND Flash Chip Programmer with computer and have the WiFi unbound.

Step 5 — Board Swap



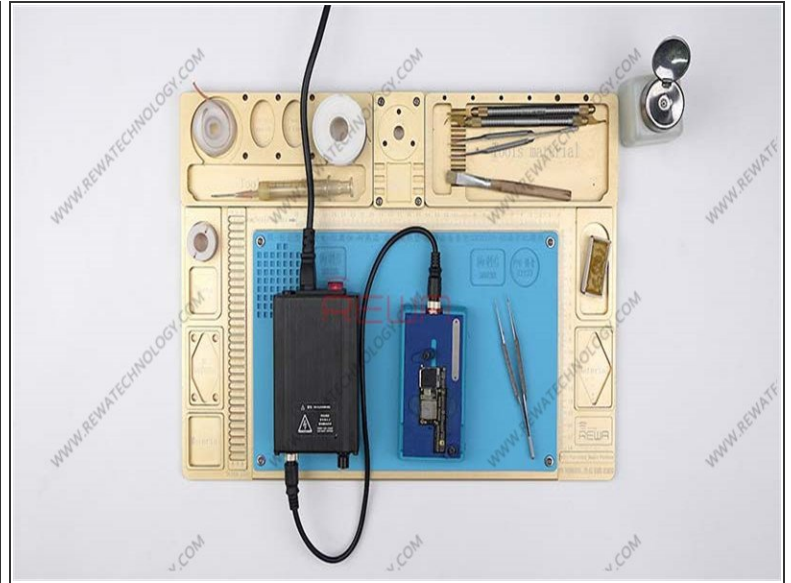
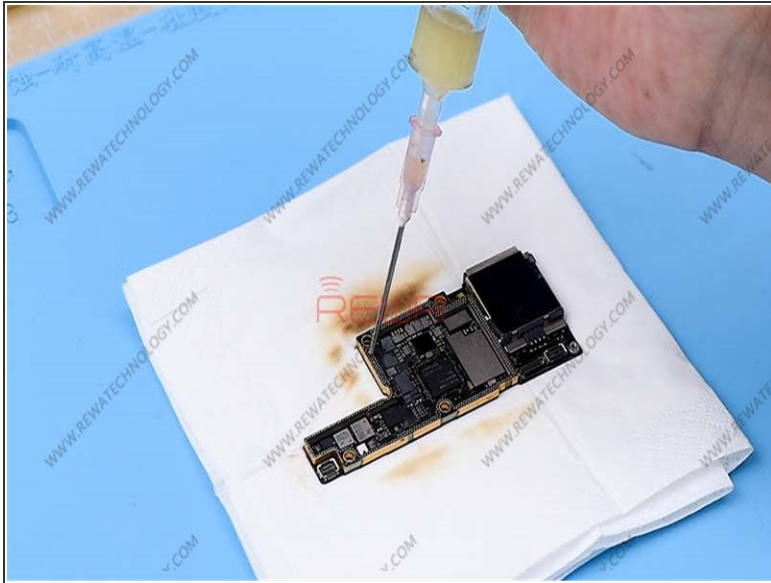
- Now, we need to solder these detached components of the original motherboard to the new motherboard.
- Apply some BGA Paste Flux to the bonding pad of the NAND flash chip and solder the chip with hot air gun.
- Continue to solder CPU, EEPROM, baseband CPU and the baseband EEPROM with the same steps.

Step 6 — Test



- Next thing we do is to solder the two layers back together. Before soldering, attach the upper layer and the lower layer to the test fixture.
- Connect the upper layer and the lower layer with the display assembly and get the board powered on. The phone can get access to the home screen normally.

Step 7 — Motherboard Recombining



- Reball the lower layer first. Then apply some BGA Paste Flux to the third space pcb.
- Attach the reball finished lower layer to the heating platform and then solder the upper layer.

Step 8 — Reassemble And Test



- Now we can assemble the phone and test.
- Get the logic board and display assembly installed, connect the battery and press power button, the phone turns on normally. iPhone X data recovery completed successfully.

This is not a DIY repair. CPU swap should not be attempted by anyone who has not done many before if there is important data on the board. A botched CPU swap is unrecoverable.

- [iPhone 11 Series Non-Genuine Screen Warning/Important Display Message - 100% Fix](#)
- [iPhone XS Max Face ID Not Working Fixed - Dot Projector Repair](#)
- [How to Upgrade iPhone 6S 16GB Storage to 128GB](#)
- [How To Upgrade iPhone X 64GB Storage To 256GB](#)
- [How to Fix iPhone X Face ID Not Working After Screen Replacement](#)
- [iPhone X Bottom Speaker Not Working Repair](#)
- [Samsung Galaxy Note 8 Broken Screen Glass Only Repair](#)
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